



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

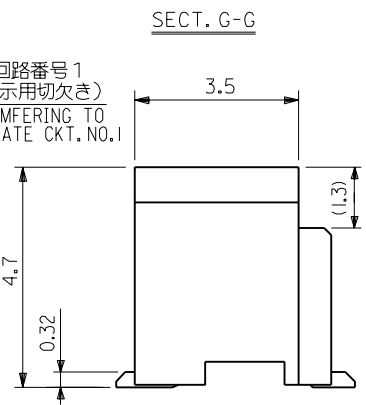
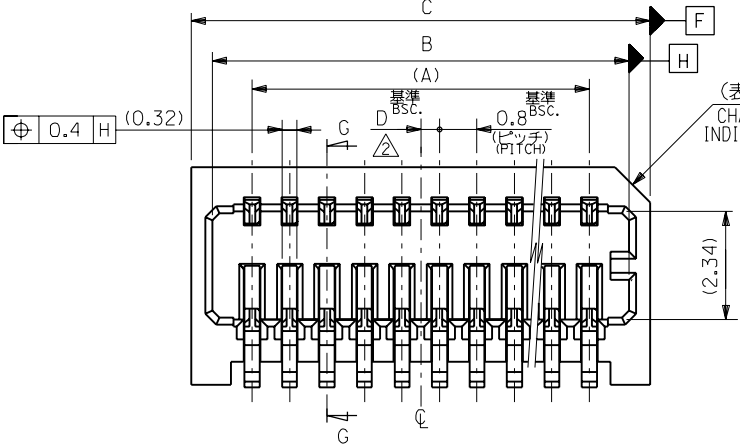
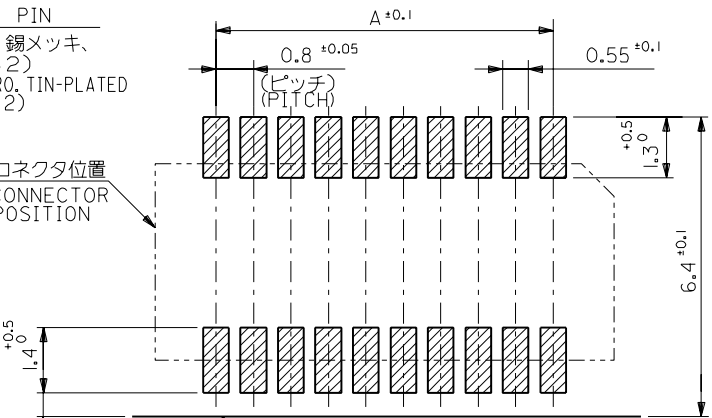
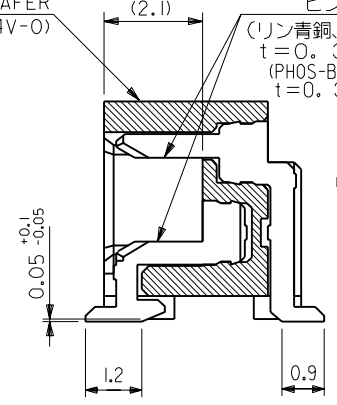
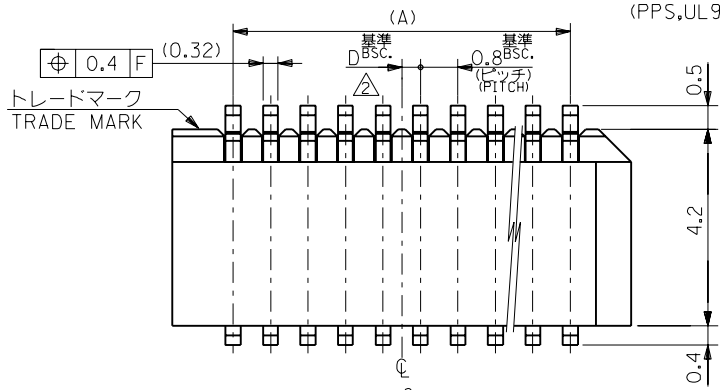
Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



ウェハ WAFER (PPS,UL94V-O)

ピン PIN (リン青銅、錫メッキ、 $t=0.32$ ) (PHOS-BRO. TIN-PLATED  $t=0.32$ )



参考基板レイアウト (マウント面)  
P.C.B. PATTERN LAYOUT (REF.) (MOUNT AREA)

0.4	17.8	16.9	15.2	53309-4027	40
0.8	17.0	16.1	14.4	-3827	38
0.4	16.2	15.3	13.6	-3627	36
0.8	15.4	14.5	12.8	-3427	34
0.4	14.6	13.7	12.0	-3227	32
0.8	13.8	12.9	11.2	-3027	30
0.4	13.0	12.1	10.4	-2827	28
0.8	12.2	11.3	9.6	-2627	26
0.4	11.4	10.5	8.8	-2427	24
0.8	10.6	9.7	8.0	-2227	22
0.4	9.8	8.9	7.2	-2027	20
0.8	9.0	8.1	6.4	-1827	18
0.4	8.2	7.3	5.6	-1627	16
0.8	7.4	6.5	4.8	-1427	14
0.4	6.6	5.7	4.0	-1227	12
0.8	5.8	4.9	3.2	53309-1027	10
D	C	B	A	ENG. NO.	極数 C.K.T.

注記 NOTES

1. 炭合相手: 52465,52588 シリーズ  
MATE WITH: 52465,52588 SERIES
- △ ウェハの C から隣接するピンの C 迄の位置を示す。  
SHOW POSITION FROM C OF WAFER TO C OF ADJACENT PINS.

角度 ANGLE	公差 TOLERANCES	記号 LTR	変更内容 REVISION RECORD	DR. CHK.	日付 DATE
30以上 OVER	+0.3	B	変更 REVISD (JC60094)	M.H.	'95/8/9
10以上 30未満 UNDER	+0.25	A	変更 REVISD (J30447)	T.C.	'93/5/1
10未満 UNDER	+0.2	O	新規作成 PROPOSED (J11001)	M.H.	'91/11/15

材料 MATERIAL	☑中参照 SEE DRAWING
仕上げ FINISH	—
適用電線範囲 WIRE RANGE	—
被覆外径 INS. RANGE	—
DRAWN BY '91/11/14	CHK'D BY '95/8/9
K.ASAKAWA	Y.M.HIRAMOTO
APP'D BY '95/8/9	尺度 SCALE
M.FUKUSHIMA	—

**molex** MOLEX-JAPAN CO.,LTD.  
日本モレックス株式会社

REVISE ONLY ON CAD SYSTEM

TITLE 名称  
0.8 BOARD TO BOARD CONN.  
WAFER ASS'Y R/A SMT  
(WITHOUT BOSS)

DWG. NO. (SHEET 1 OF 2) REV  
SD-53309-\*\*-27 B

DWG. NO. SD-53309-\*\*\*27

E

D

C

B

A

F

E

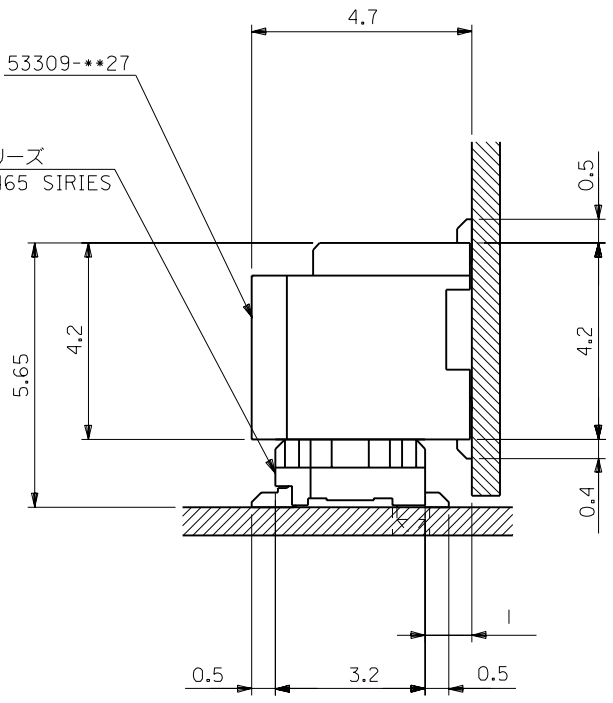
D

C

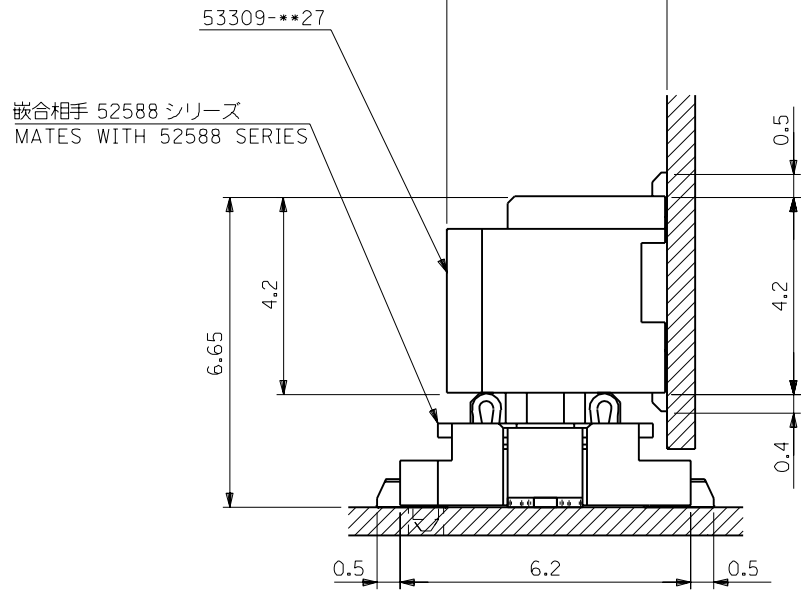
B

A

DIMENSIONS IN METRIC DO NOT SCALE DRAWING



嵌合状態図 (参考)  
MATED DRAWING(REF.)



嵌合状態図 (参考)  
MATED DRAWING(REF.)

<b>角度 ANGLE</b> 30°以上 OVER +0.3 10°以上 30°未満 UNDER -0.25 未満 10° UNDER +0.2 一般公差 GENERAL TOLERANCES		<b>記号 LTR</b> 変更内容 REVISION RECORD DR. CHR. DATE		<b>材料 MATERIAL</b> SHEET 1 OF 2 参照 REFER TO SHEET 1 OF 2 <b>仕上げ FINISH</b> — <b>適用電線範囲 WIRE RANGE</b> — <b>被覆外径 INS. RANGE</b> — DRAWN BY '95/11/14 K.ASAKAWA APP'D BY '95/8/9 M.FUKUSHIMA		<b>MOLEX</b> MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社 <b>REVISE ONLY ON CAD SYSTEM</b> TITLE 名称 0.8 BOARD TO BOARD CONN. WAFER ASS'Y R/A SMT (WITHOUT BOSS) DWG. NO. (SHEET 2 OF 2) REV SD-53309-***27 B	
<b>REVISION RECORD</b> 変更内容 REVISION RECORD 記号 LTR 変更内容 REVISION RECORD 記号 LTR		<b>REVISION RECORD</b> 変更内容 REVISION RECORD 記号 LTR 変更内容 REVISION RECORD 記号 LTR		<b>REVISION RECORD</b> 変更内容 REVISION RECORD 記号 LTR 変更内容 REVISION RECORD 記号 LTR		<b>REVISION RECORD</b> 変更内容 REVISION RECORD 記号 LTR 変更内容 REVISION RECORD 記号 LTR	

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX(JAPAN) AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION  
 本図面は日本モレックス(株)の所有する情報を含むもので 当社の許可なく複製を禁止する。  
 EN-OIC(032)MXJ-32

8

7

6

5

4

3

2

1

SD-53309-S12

DWG. NO. SD-53309-\*\*-91

E

D

C

B

A

DIMENSIONS IN METRIC DO NOT SCALE DRAWING

8 7 6 5 4 3 2 1

引き出し方向  
PULL OUT DIRECTION

注記 NOTES

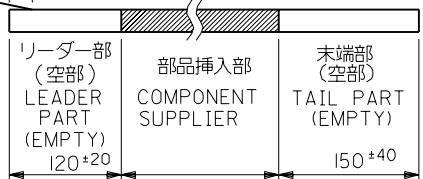
1. 梱包数量：1000個/リール NUMBER OF CONNECTORS:1000PCS/REEL

2. リードテープ長さ LEAD TAPE LENGTH

トップテープ TOP TAPE  
リーダー部 LEADER PART  
未接着部 NON-BONDED PART

175 ±25 25 ±5

引き出し方向  
PULL OUT DIRECTION



3. トップテープの剥離強度：(剥離方向は下図参照)

0.1N~0.7N(10.2gf~71.4gf)尚、本規格値は、出荷時に適用。

(但し、輸送時に剥離が発生しない事。)

PEELING OFF FORCE OF TOP TAPE

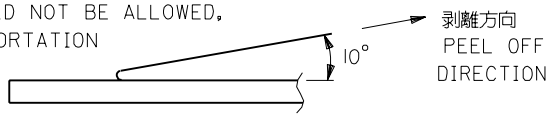
0.1N~0.7N(10.2gf~71.4gf)(PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)

THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT

PEEL OFF SHOULD NOT BE ALLOWED,

DURING TRANSPORTATION

引き出し方向  
PULL OUT DIRECTION



剥離方向  
PEEL OFF DIRECTION

4. 材料

キャリアテープ：ポリプロピレン (PP)

トップテープ：PET, PE, PEF

リール：ポリスチレン (PS)

<リサイクル材を含む>

MATERIAL

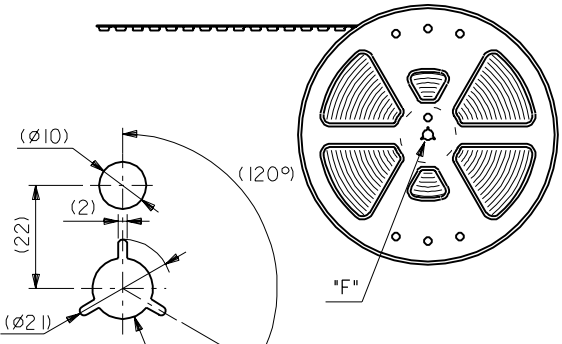
CARRIER TAPE:POLYPROPYLENE

TOP TAPE:PET,PE,PEF

REEL:POLYSTYRENE(PS)

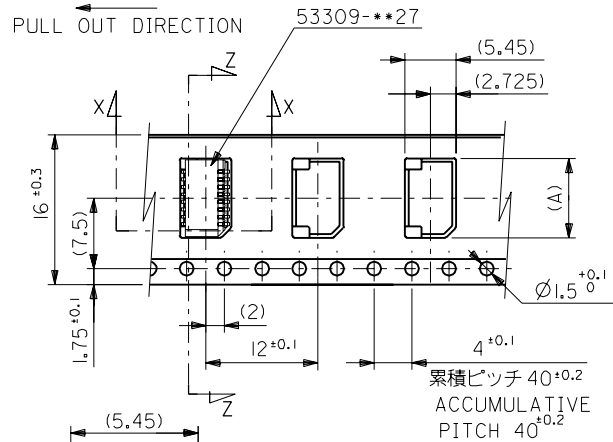
<RECYCLE MATERIAL CONTAINED>

16	17.5	9.3	53309-1891	18
		8.5	53309-1691	16
		7.7	53309-1491	14
		6.9	53309-1291	12
6.1	53309-1091	10		
キャリアテープ幅 CARRIER TAPE WIDTH	B	(A)	ENG. NO.	極数 CIRCUIT

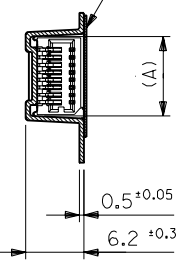


DETAIL "F"

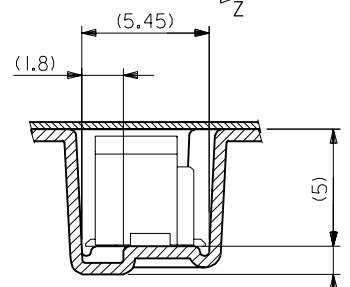
引き出し方向  
PULL OUT DIRECTION



トップテープ  
TOP TAPE



SECT. Z-Z



SECT. X-X  
(SCALE 5:1)

16mm幅キャリアテープ  
16mm WIDTH CARRIER TAPE

角度 ANGLE	±3°	C	変更 REVISION	(JC2001-0421)	100/12/6
30°以上 OVER	+0.3	B	変更 REVISION	(JC60709)	96/4/3
10°以上 30° UNDER	+0.25	A	変更 REVISION	(J30447)	93/5/11
10° UNDER	+0.2	O	新規作成 PROPOSED	(J11065)	91/11/22
一般公差 GENERAL TOLERANCES	記号 LTR	変更内容 REVISION RECORD	DR. DATE	日付 DATE	尺度 SCALE

材料 MATERIAL	注記参照 SEE NOTES
仕上げ FINISH	—
適用電線範囲 WIRE RANGE	—
被覆外径 INS. RANGE	—
DRAWN BY '91/11/22 K.ASAKAWA	CHK'D BY '00/12/6 T.ITO
APP'D BY '00/12/6 M.FUKUSHIMA	尺度 SCALE

MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社	
REVISE ONLY ON CAD SYSTEM	
TITLE 名称	
0.8 BtB Conn Wafer Assy	
RA SMT Without Boss	
Embstop Pkg	
DWG. NO. (SHEET 1 OF 2)	REV
SD-53309-**-91	C

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX(JAPAN) AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION  
本図面は日本モレックス(株)の所有する情報を含むもので 会社の許可なく複製を禁止する。

EN-01C(032)MXJ-32

8 7 6 5 4 3 2 1

F

E

D

C

B

A

5949923A.S07

DWG. NO.  
SD-53309-\*\*-91

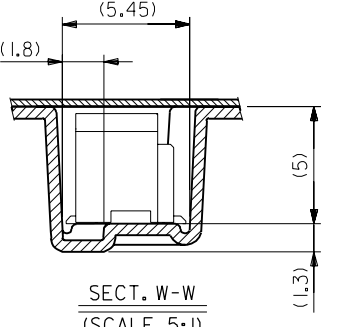
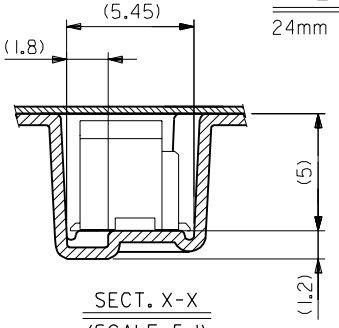
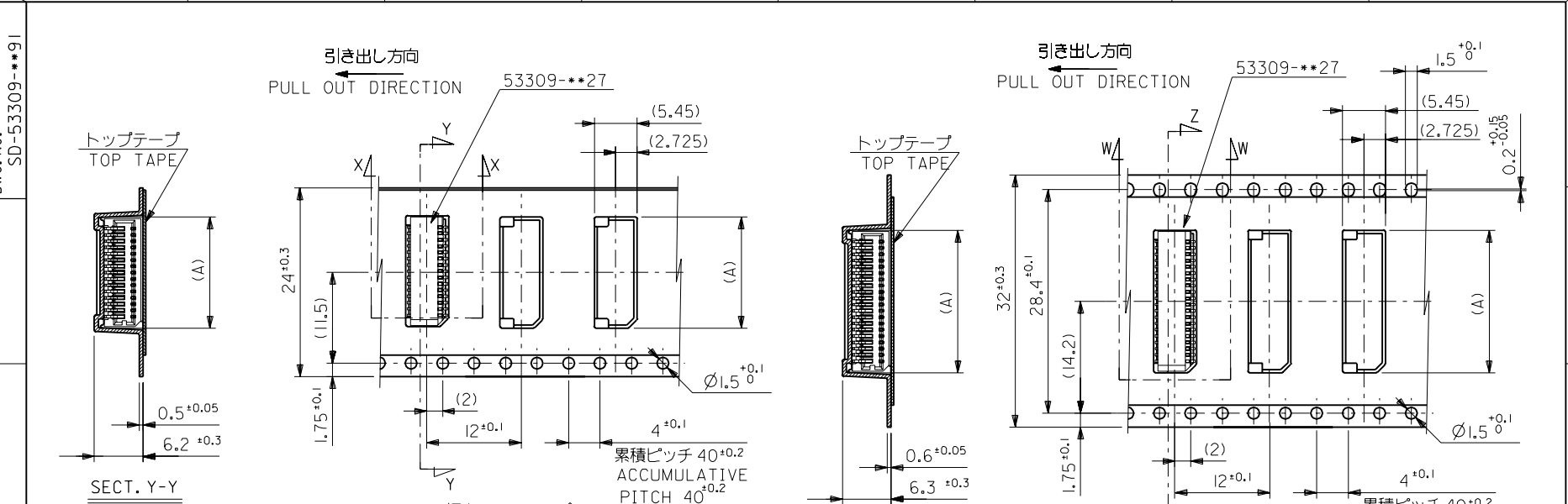
E

D

C  
DIMENSIONS IN METRIC DO NOT SCALE DRAWING

B

A



24	25.5	16.5	53309-3691	36
		15.7	53309-3491	34
		14.9	53309-3291	32
		14.1	53309-3091	30
		13.3	53309-2891	28
		12.5	53309-2691	26
		11.7	53309-2491	24
		10.9	53309-2291	22
		10.1	53309-2091	20
キャリアテープ幅 CARRIER TAPE WIDTH	B	(A)	ENG. NO.	極数 CIRCUIT

32	33.5	18.1	53309-4091	40
キャリアテープ幅 CARRIER TAPE WIDTH	B	(A)	ENG. NO.	極数 CIRCUIT
材料 MATERIAL		SHEET 1 OF 2参照 REFER TO SHEET 1 OF 2		
仕上げ FINISH		—		
適用電線範囲 WIRE RANGE		—		
被覆外径 INS. RANGE		—		
DRAWN BY '91/11/22 K.ASAKAWA		CHK'D BY '00/12/6 T.ITO		
APP'D BY '00/12/6 M.FUKUSHIMA		尺度 SCALE —		
DWG. NO. (SHEET 2 OF 2) REV		SD-53309-**-91 C		

角度 ANGLE	±3°	C	変更 REVISED (JC2001-0421)	100/12/6
30°以上 OVER	+0.5	B	変更 REVISED (JC60709)	96/4/3
10°以上 30°未満 OVER UNDER	+0.25	A	変更 REVISED (J30447)	93/5/11
10°未満 UNDER	+0.2	O	新規作成 PROPOSED (J11065)	91/11/22
一般公差 GENERAL TOLERANCES		記号 LTR	変更内容 REVISION RECORD	DR. CHR.

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX (JAPAN) AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION  
本図面は日本モレックス(株)の所有する情報を含むもので 当社の許可なく複製を禁止する。  
EN-OIC(032)MXJ-32

59499234.S08